



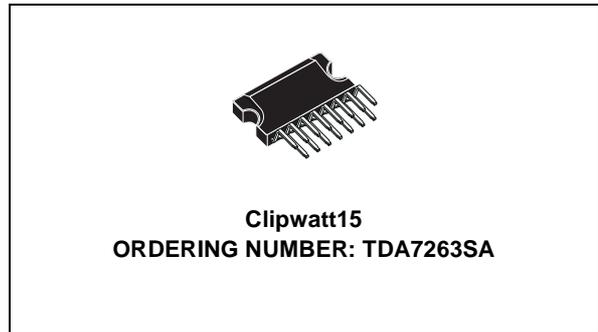
TDA7263SA

12 + 12W STEREO AMPLIFIER WITH MUTING

- WIDE SUPPLY VOLTAGE RANGE
- HIGH OUTPUT POWER
12+12W @ $V_S=28V$, $R_L = 8\Omega$, THD=10%
- MUTE FACILITY (POP FREE) WITH LOW CONSUMPTION
- AC SHORT CIRCUIT PROTECTION
- THERMAL OVERLOAD PROTECTION

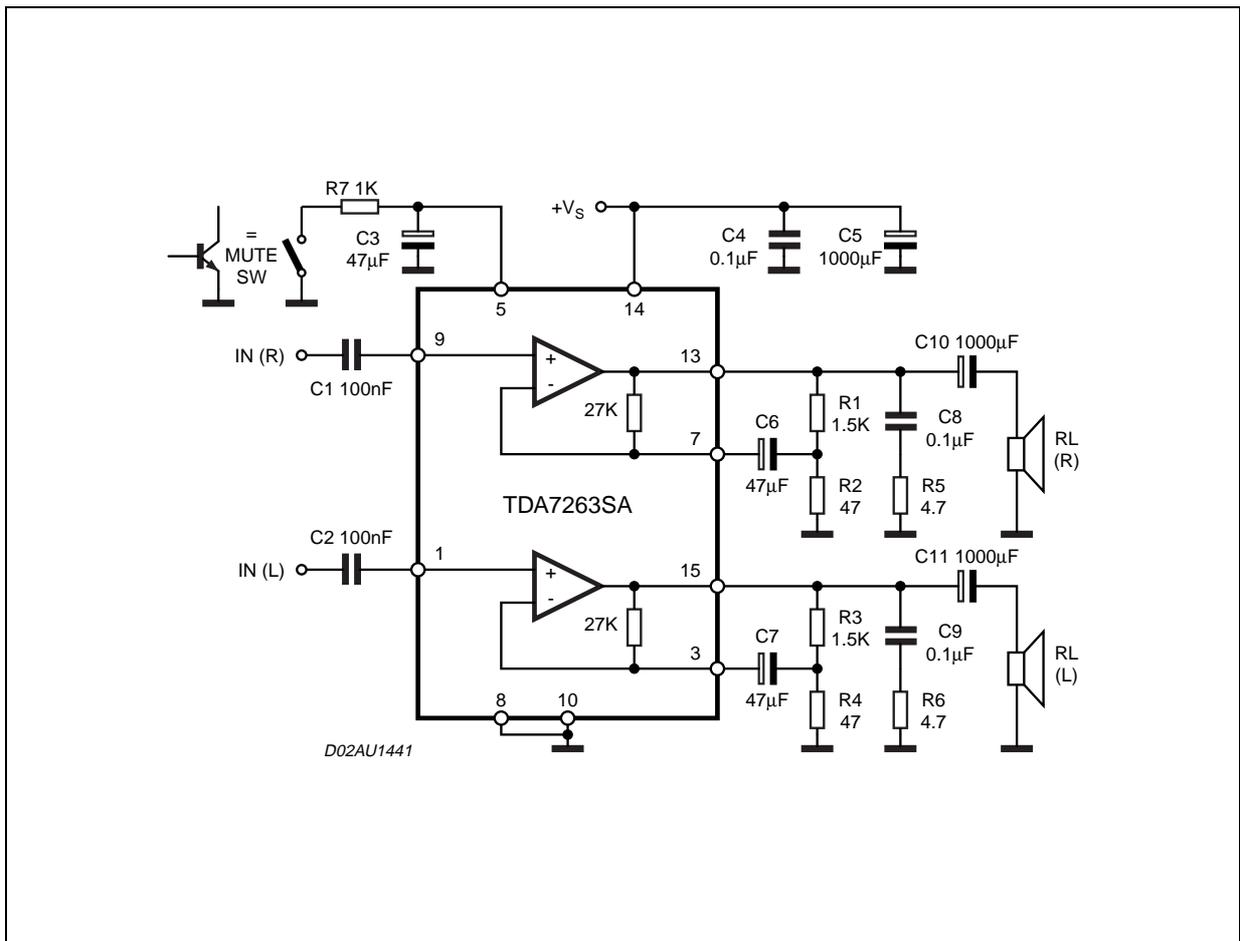
DESCRIPTION

The TDA7263SA is class AB dual audio power amplifier assembled in the Clipwatt package, specially designed for high quality sound application as HI-FI music centers and stereo TV sets.



Pin to pin compatible with the TDA7253L, TDA7263L

TEST AND APPLICATION DIAGRAM

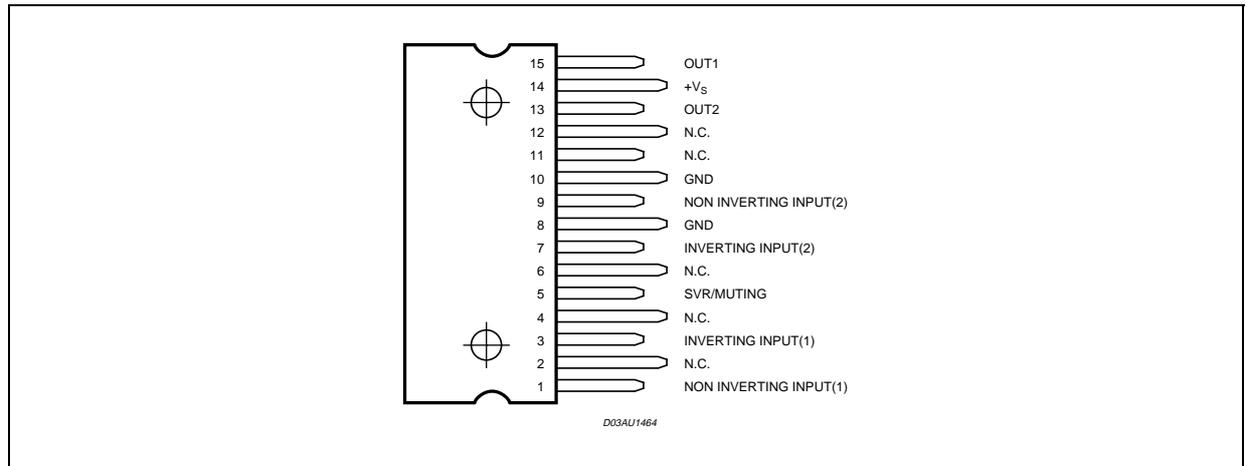


TDA7263SA

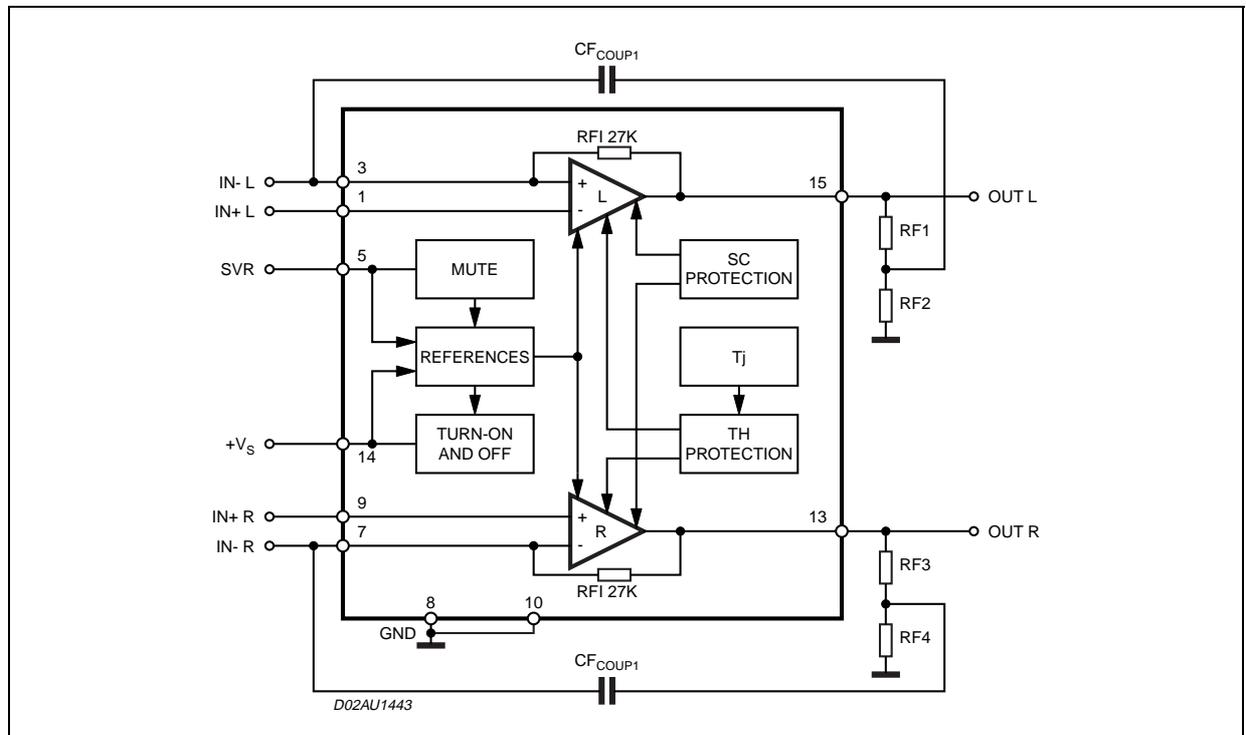
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_S	Supply Voltage without Load	35	V
I_O	Output Peak Current (repetitive $f > 20\text{Hz}$)	2.5	A
I_O	Output Peak Current (non repetitive, $t = 100\mu\text{s}$)	3.5	A
P_{tot}	Total Power Dissipation ($T_{case} = 70^\circ\text{C}$)	20	W
T_{op}	Operating Temperature Range	0 to 70	$^\circ\text{C}$
T_{stg}, T_j	Storage & Junction Temperature	-40 to 150	$^\circ\text{C}$

PIN CONNECTION (Top view)



BLOCK DIAGRAM



THERMAL DATA

Symbol	Parameter	Value	Unit
$R_{th\ j-case}$	Thermal resistance junction to case	Max 3.5	°C/W

ELECTRICAL CHARACTERISTICS (Refer to the stereo test and application circuit, $V_S = 28V$; $R_L = 8\Omega$; $G_V = 30dB$; $f = 1KHz$; $T_{amb} = 25^\circ C$ unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V_S	Supply Voltage		10		32	V
V_O	Quiescent Output Voltage			13.5		V
I_q	Total Quiescent Current			70	95	mA
P_O	Output Power (RMS)	$d = 10\%$; $T_{amb} = 85^\circ C$	10	12		W
		$d = 1\%$		9.5		W
d	Total Harmonic Distortion	$P_O = 1W$, $f = 1kHz$		0.02	0.2	%
		$f = 100Hz$ to $10KHz$; $P_O = 0.1$ to $8W$			0.5	%
C_T	Cross Talk	$R_S = 10K\Omega$; $f = 1KHz$		70		dB
		$R_S = 10K\Omega$; $f = 10KHz$		60		dB
R_I	Input Resistance		100	200		$K\Omega$
f_L	Low Frequency Roll-off (-3dB)			40		Hz
f_H	High Frequency Roll-off (-3dB)			80		KHz
e_N	Total Input Noise Voltage	A Curve; $R_S = 10K\Omega$		1.5		mV
		$f = 22Hz$ to $22KHz$; $R_S = 10K\Omega$		3	10	V
SVR	Supply Voltage Rejection (each channel)	$R_S = 10K\Omega$; $f = 100Hz$; $V_r = 0.5V$	45	60		dB
T_j	Thermal Shutdown Junction Temperature			145		°C
MUTE FUNCTION						
V_{TMUTE}	Mute Threshold		1	1.6		V
V_{TPLAY}	Play Threshold			4.5		V
ATT_{AM}	Mute Attenuation		70	100		dB
I_{qMUTE}	Quiescent Current @ Mute			7	10	mA

TYPICAL CHARACTERISTICS (referred to the typical Application Circuit, $V_S = 28V$, $R_L = 8\Omega$, unless otherwise specified)

Figure 1. Output Power vs. Supply Voltage

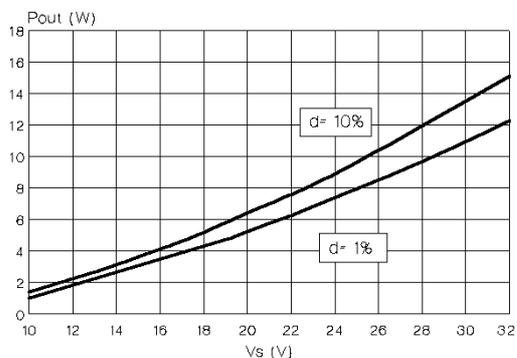


Figure 2. Distortion vs. Output Power

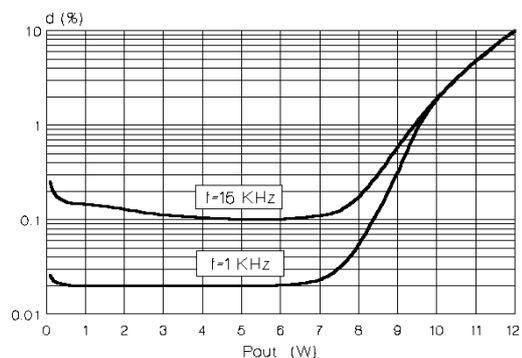


Figure 3. Quiescent Current vs. Supply Voltage

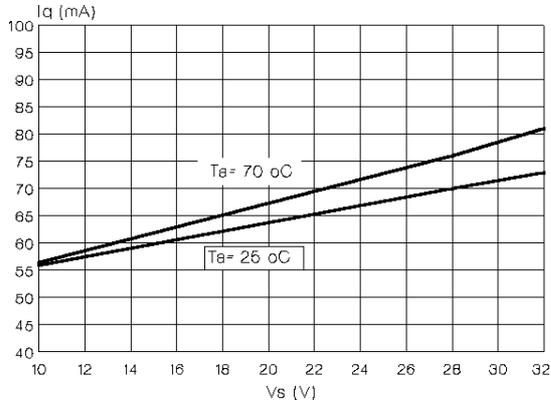


Figure 6. Output Attenuation & Quiescent Current vs. V_{pin5}

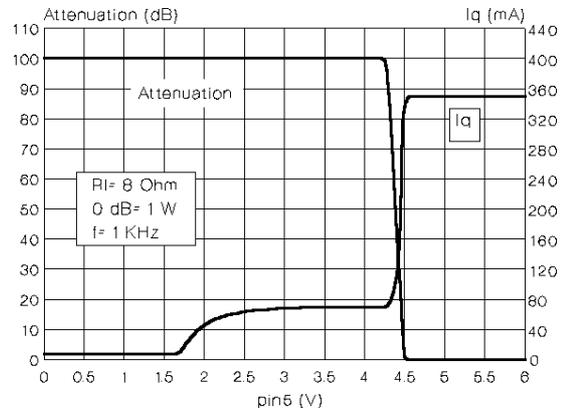


Figure 4. Supply Voltage Rejection vs. Freq.

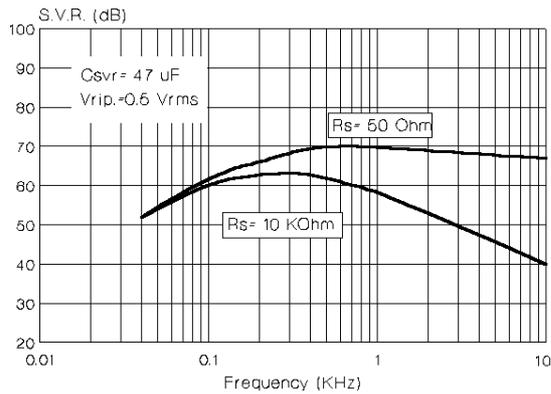


Figure 7. Total Power Dissipation vs. Output Power

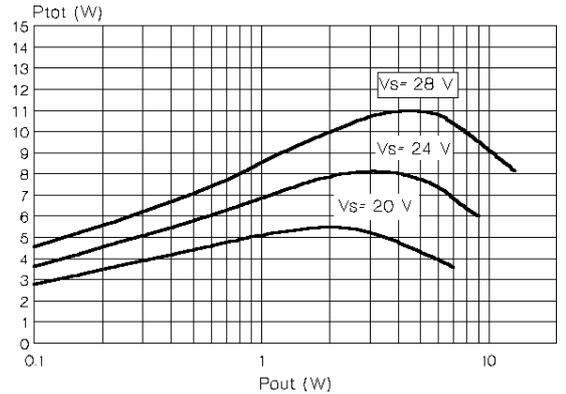
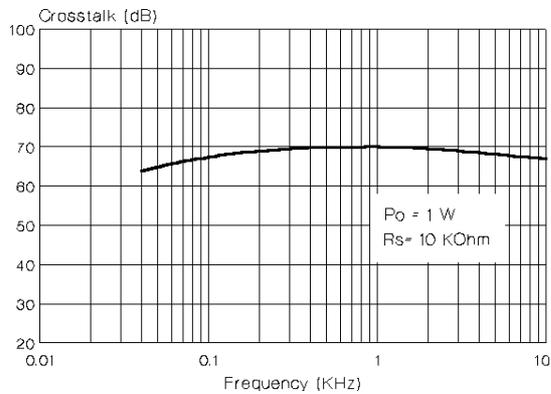


Figure 5. Crosstalk vs. Frequency



BUILT-IN PROTECTION SYSTEMS

Thermal Shut-down

The presence of a thermal limiting circuit offers the following advantages:

- 1 an overload on the output (even if it is permanent), or an excessive ambient temperature can be easily withstood.
- 2 the heatsink can have a smaller factor of safety compared with that of a conventional circuit. There is no device damage in the case of excessive junction temperature; all that happens is that P_O (and therefore P_Q) and I_O are reduced.

Short Circuit (AC Conditions)

The TDA7263SA can withstand accidental short circuits across the speaker made by a wrong connection during normal play operation.



HEAT SINK DIMENSIONING:

In order to avoid the thermal protection intervention, that is placed approximatively at $T_j = 150^\circ\text{C}$, it is important the dimensioning of the Heat Sink R_{Th} ($^\circ\text{C}/\text{W}$).

The parameters that influence the dimensioning are:

- Maximum dissipated power for the device (P_{dmax})
- Max thermal resistance Junction to case ($R_{Th\ j-c}$)
- Max. ambient temperature $T_{amb\ max}$
- Quiescent current I_q (mA)

Example:

$V_{CC} = 28\text{V}$, $R_{load} = 80\text{ohm}$, $R_{Th\ j-c} = 3.5\ ^\circ\text{C}/\text{W}$, $T_{amb\ max} = 50^\circ\text{C}$

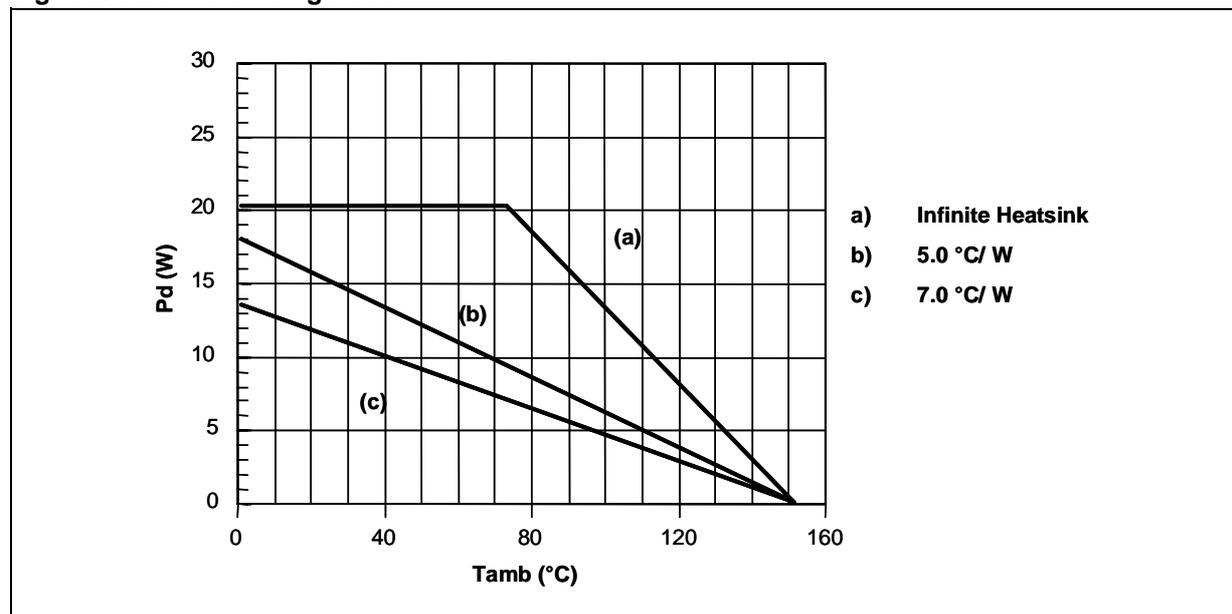
$$P_{dmax} = (N^\circ \text{ channels}) \cdot \frac{V_{cc}^2}{2\Pi^2 \cdot R_{load}} + I_q \cdot V_{cc}$$

$$P_{dmax} = 2 \cdot (4.9) + 1.9 = 11.3\text{W}$$

$$(\text{Heat Sink}) R_{Th\ c-a} = \frac{150 - T_{amb\ max}}{P_{d\ max}} - R_{Th\ j-c} = \frac{150 - 50}{11.3} - 3.5 = 5.3^\circ\text{C}/\text{W}$$

In figure 8 is shown the Power derating curve for the device.

Figure 8. Power derating curve



Clipwatt Assembling Suggestions

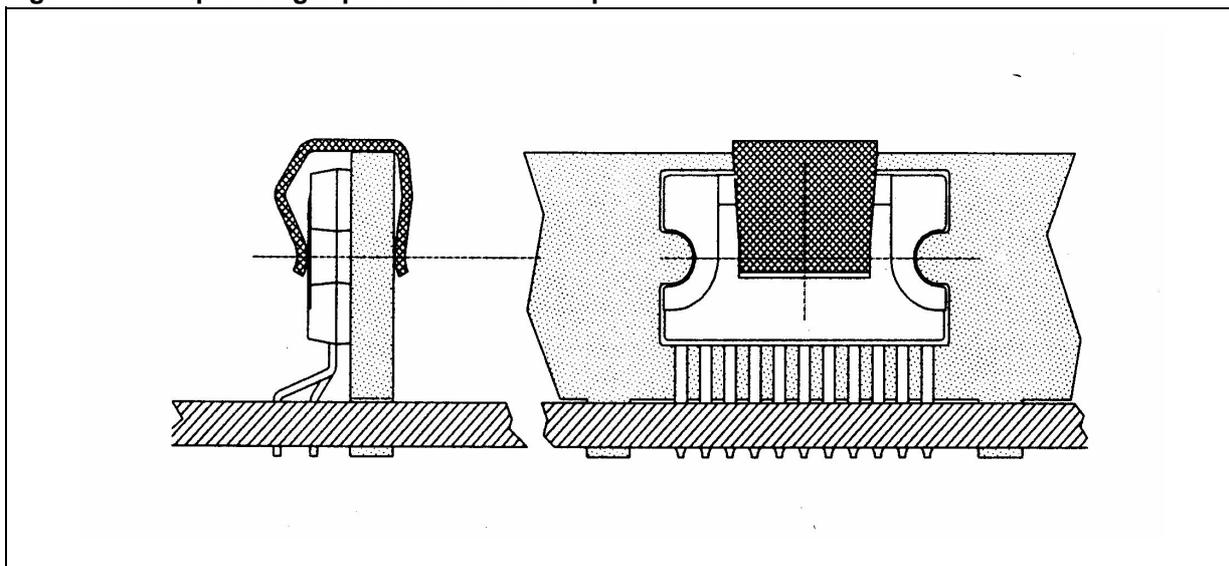
The suggested mounting method of Clipwatt on external heat sink, requires the use of a clip placed as much as possible in the plastic body center, as indicated in the example of figure 9.

A thermal grease can be used in order to reduce the additional thermal resistance of the contact between package and heatsink.

A pressing force of 7 - 10 Kg gives a good contact and the clip must be designed in order to avoid a maximum contact pressure of 15 Kg/mm² between it and the plastic body case.

As example , if a 15Kg force is applied by the clip on the package , the clip must have a contact area of 1mm² at least.

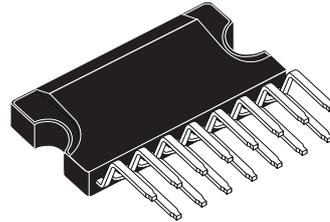
Figure 9. Example of right placement of the clip



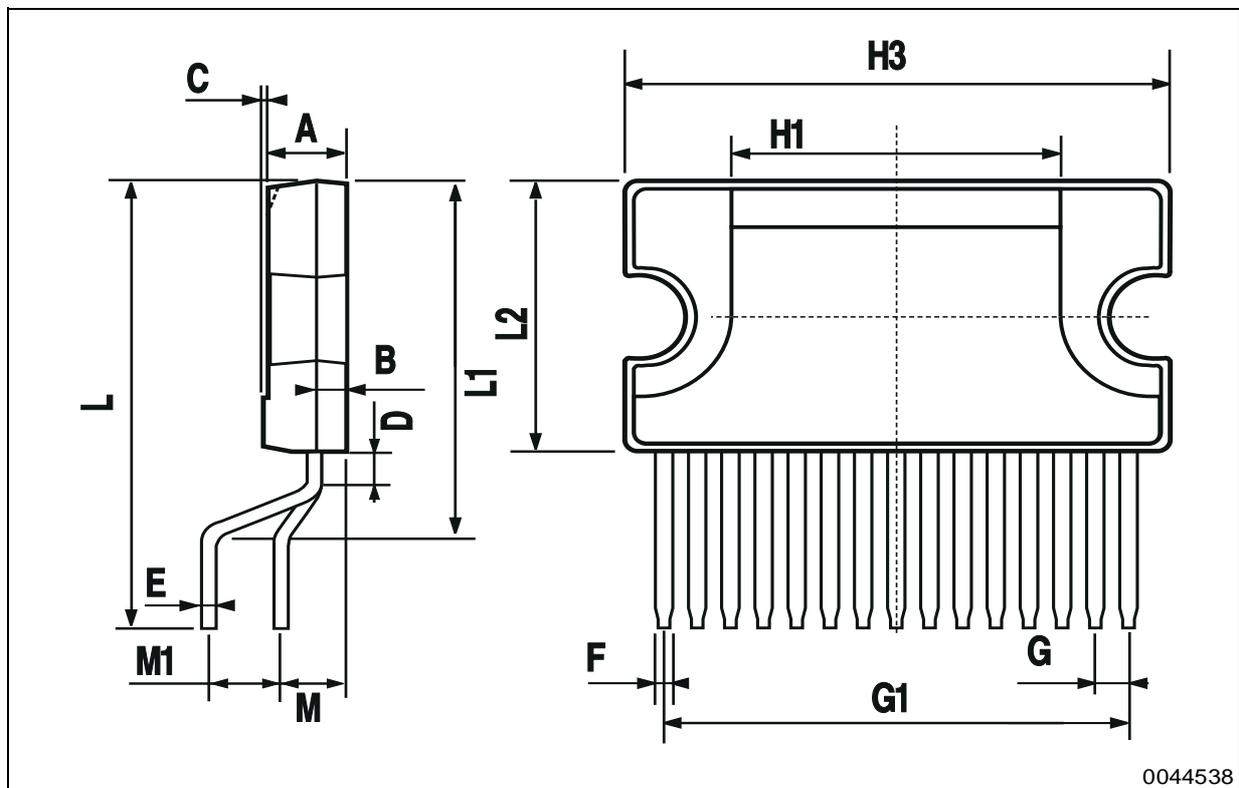
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			3.2			0.126
B			1.05			0.041
C		0.15			0.006	
D		1.55			0.061	
E	0.49		0.55	0.019		0.022
F	0.67		0.73	0.026		0.029
G	1.14	1.27	1.4	0.045	0.050	0.055
G1	17.57	17.78	17.91	0.692	0.700	0.705
H1		12			0.480	
H2		18.6			0.732	
H3	19.85			0.781		
L		17.95			0.707	
L1		14.45			0.569	
L2	10.7	11	11.2	0.421	0.433	0.441
L3		5.5			0.217	
M		2.54			0.100	
M1		2.54			0.100	

OUTLINE AND MECHANICAL DATA

Weight: 1.92gr



Clipwatt15



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